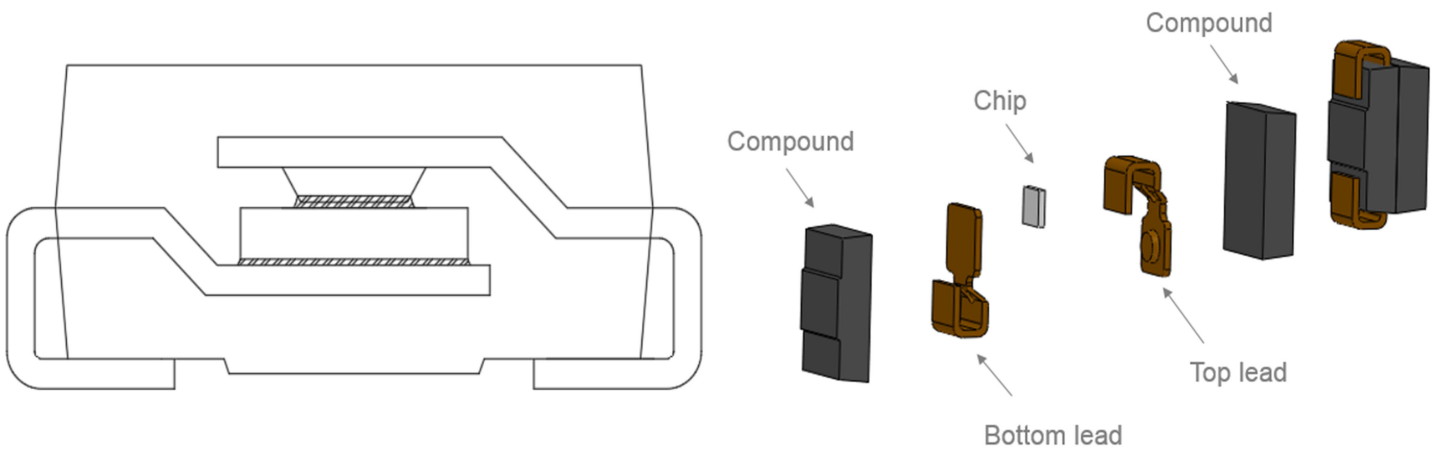


SMB

1: Certification

- System:
 - IATF 16949
 - ISO9001
 - ISO14001
 - ISO45001
- ROHS/REACH/ELV:
 - Lead frame、Solder, Molding compound、Post plating.
- UL 94: V-0
- MSL : level 1
- Whisker Test: JESD 201 class 2
- Solder bath temperature : 260°C maximum, 10 s

2: Internal Structure Diagram



Meet Die Size

	Lead Pad(mm)	Die size(mil)	Wafer thickness (um)
Max	2.40	90.00	350.00
Min	0.82	32.00	110.00

3: Production line advantage

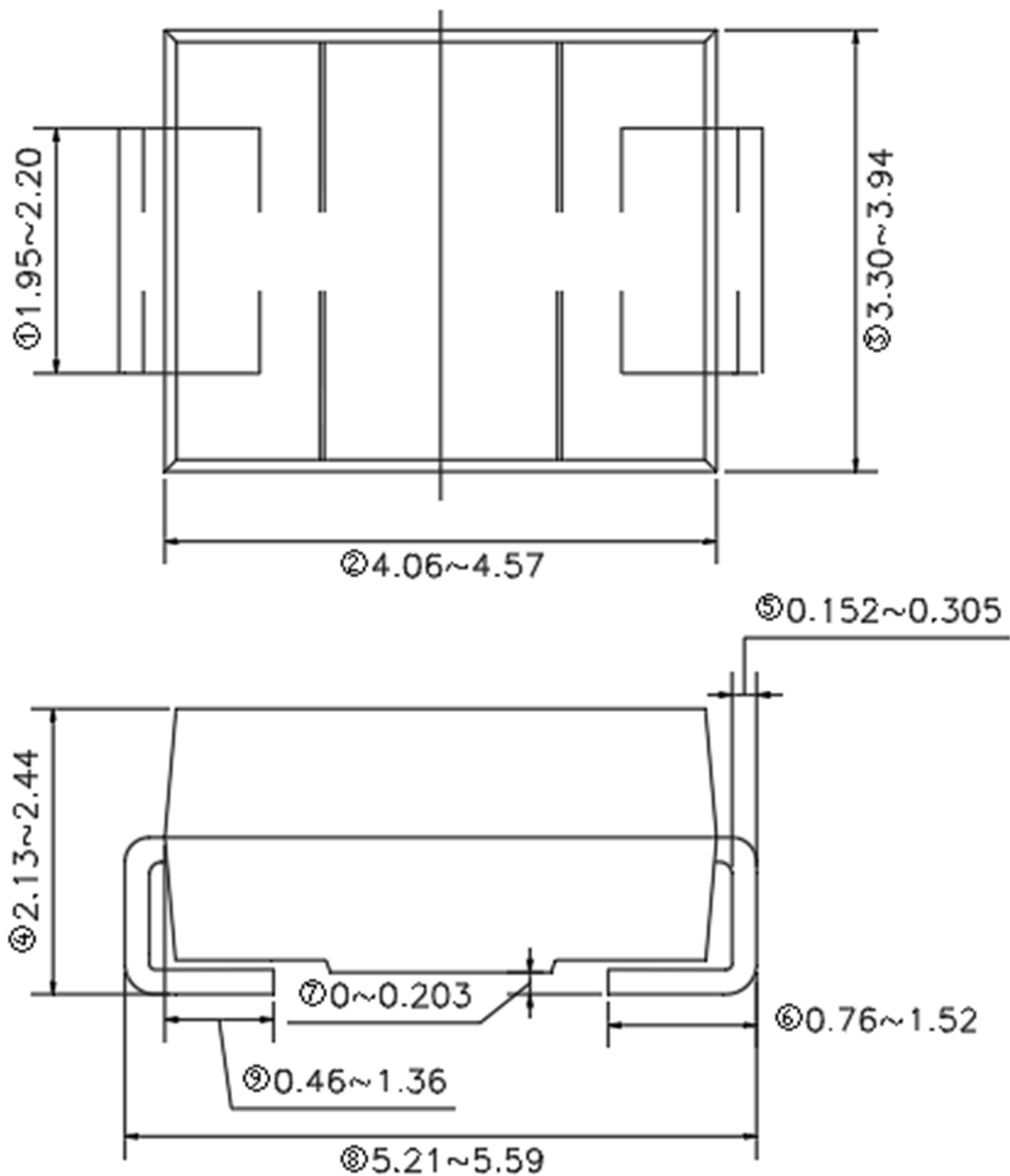
- 100% AOI in TMTT.
- Automated production line for all process.

4: Reliability Experiment

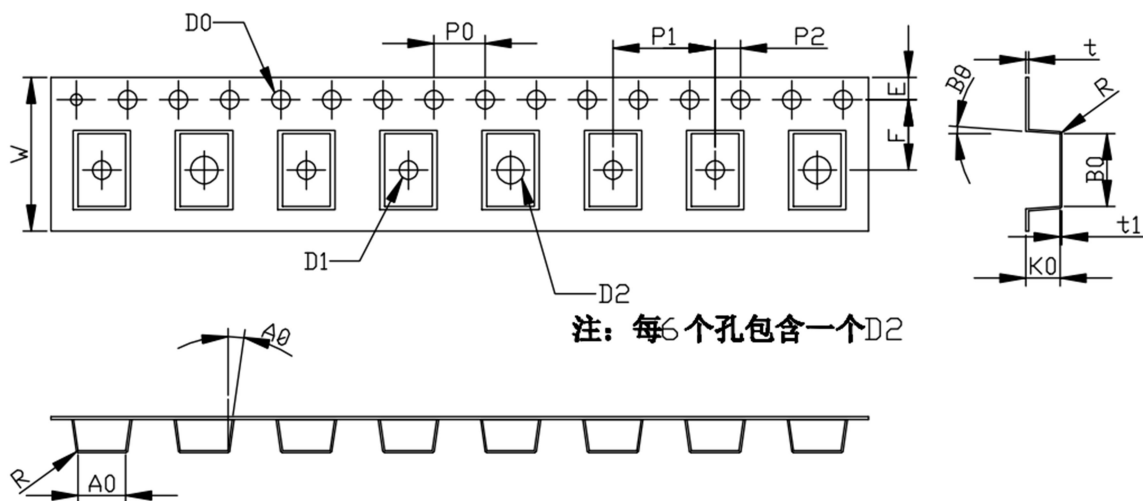
Test	Test Condition
HAST	80%VR/130°C/85%R.H.
Temp. Cycling	1000 cycles form -55°to 150°C
UHAST	96 hours at Ta = 130°C, RH = 85%
HTRB	1000 hours 150°
RSH	260°C , 10 s

5: Package Outline Dimensions in millimeters

5.1 POD



5.2 Package (tape & carrier) Dimensions in millimeters



Symbol	Spec	Symbol	Spec
W	$12.00^{+0.3}_{-0.1}$	A ₀	3.76 ± 0.10
E	1.75 ± 0.10	B ₀	5.69 ± 0.10
F	5.50 ± 0.05	K ₀	2.67 ± 0.10
D ₀	$1.50^{+0.1}_{-0.0}$	t	0.23 ± 0.03
D ₁	$1.50^{+0.25}_{-0.0}$	t1	≥ 0.10
D ₂	$1.70^{+0.05}_{-0.00}$	A ₀	8° MAX
P ₀	4.00 ± 0.10	B ₀	4° MAX
P ₁	8.00 ± 0.10	R	0.13MAX
P ₂	2.00 ± 0.05		